

INTEGRATED MANUFACTURING PACKAGING PROCESS

ABSTRACT

A process of fabricating a circuitized substrate is provided which comprises the steps of: providing an organic substrate (12) having circuitry thereon; applying a dielectric film on the organic substrate (12); forming microvias in said dielectric film (16); sputtering a metal seed layer (20) on the dielectric film (16), and in said microvias; plating a metallic layer (22) on the metal seed layer (20); and forming a circuit pattern thereon.

Fig.1.